AP2101/AP2111

2A SINGLE CHANNEL CURRENT-LIMITED POWER SWITCH

Features

- Single USB port power switches with auto-discharge
- Short-circuit current and thermal protection
- 2.45A accurate current limiting
- Fast transient response time: 5μs
- 90mΩ on-resistance
- Reverse Current Blocking
- Input voltage range: 2.7V – 5.5V
- 0.6ms typical rise time
- Very low shutdown current: 1μA (max)
- Fault report (FLG) with blanking time (7ms typ)
- ESD protection: 4KV HBM, 300V MM
- Active low (AP2101) or active high (AP2111) enable
- Ambient temperature range: -35°C to 85°C
- SOP-8L and MSOP-8L-EP (Exposed Pad): Available in "Green" Molding Compound (No Br, Sb)
- Lead Free Finish / RoHS Compliant (Note 1)
- UL Recognized, File Number E322375 (pending)
- IEC60950-1 CB Scheme Certified

Description

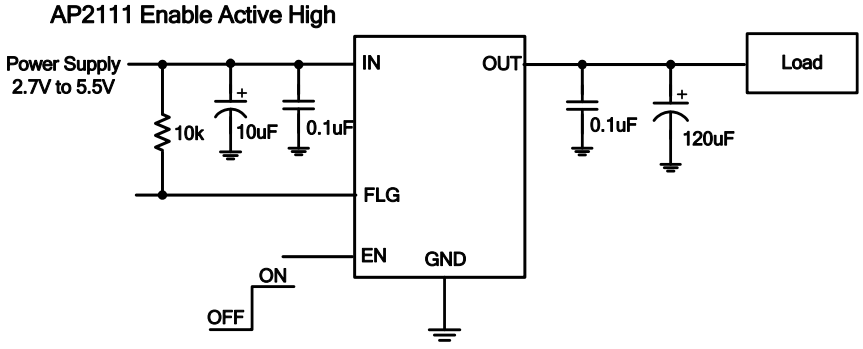
The AP2101 and AP2111 are integrated high-side power switches optimized for Universal Serial Bus (USB) and other hot-swap applications. The family of devices complies with USB 2.0 and available with both polarities of Enable input. They offer current and thermal limiting and short circuit protection as well as controlled rise time, under-voltage lockout and auto-discharge functionalities. A 7ms deglitch capability on the open-drain Flag output prevents false over-current reporting and does not require any external components.

All devices are available in SOP-8L and MSOP-8L-EP packages.

Applications

- Consumer electronics – LCD TV & Monitor, Game Machines
- Communications – Set-Top-Box, GPS, Smartphone
- Computing – Laptop, Desktop, Servers, Printers, Docking Station, HUB

Typical Application Circuit

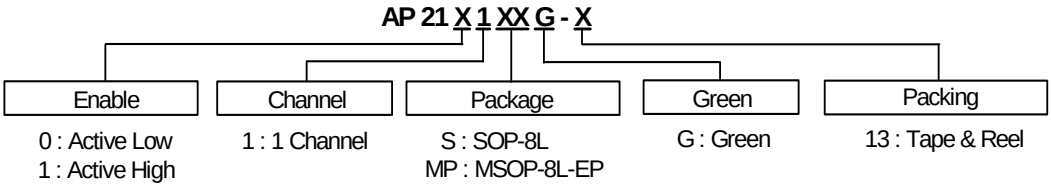


Available Options

Part Number	Channel	Enable pin (EN)	Current limit (typical)	Recommended maximum continuous load current
AP2101	1	Active Low	2.45A	2.0A
AP2111	1	Active High	2.45A	2.0A

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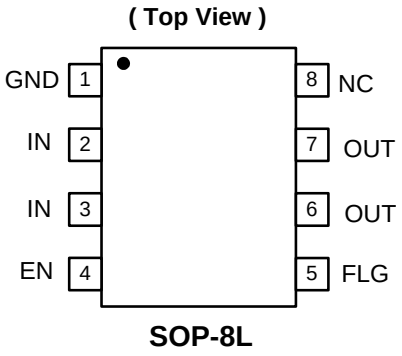
Ordering Information



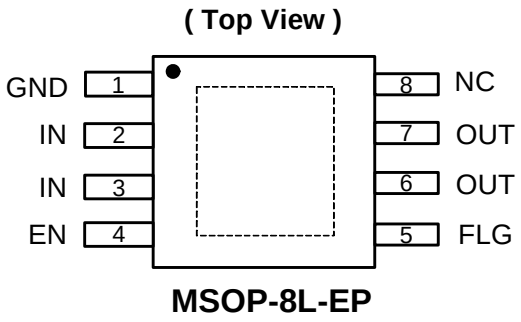
Device	Package Code	Packaging (Note 2)	13" Tape and Reel	
			Quantity	Part Number Suffix
AP21X1SG-13	S	SOP-8L	2500/Tape & Reel	-13
AP21X1MPG-13	MP	MSOP-8L-EP	2500/Tape & Reel	-13

Notes: 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied. Please visit our website at http://www.diodes.com/products/lead_free.html
2. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

Pin Assignment



SOP-8L



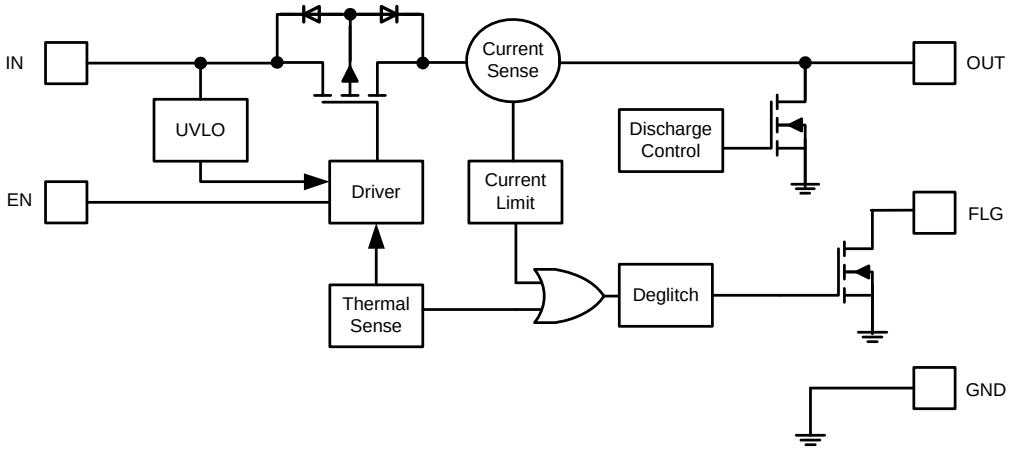
MSOP-8L-EP

Pin Descriptions

Pin Name	Pin Number	Descriptions
GND	1	Ground
IN	2, 3	Voltage input pin (all IN pins must be tied together externally)
EN	4	Enable input, active low (AP2101) or active high (AP2111)
FLG	5	Over-current and over-temperature fault report; open-drain flag is active low when triggered
OUT	6, 7	Voltage output pin (all OUT pins must be tied together externally)
NC	8	No internal connection; recommend tie to OUT pins

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Functional Block Diagram



Absolute Maximum Ratings

Symbol	Parameter	Ratings	Units
ESD HBM	Human Body Model ESD Protection	4	KV
ESD MM	Machine Model ESD Protection	300	V
V_{IN}	Input Voltage	6.5	V
V_{OUT}	Output Voltage	V_{IN} + 0.3	V
V_{EN} , V_{FLG}	Enable Voltage	6.5	V
I_{load}	Maximum Continuous Load Current	Internal Limited	A
T_{Jmax}	Maximum Junction Temperature	150	°C
T_{ST}	Storage Temperature Range (Note 3)	-65 to 150	°C

Notes: 3. UL Recognized Rating from -30°C to 70°C (Diodes qualified T_{ST} from -65°C to 150°C)

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
V_{IN}	Input voltage	2.7	5.5	V
I_{OUT}	Output Current	0	2.0	A
T_A	Operating Ambient Temperature	-35	85	°C

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Electrical Characteristics

(T_A = 25°C, V_{IN} = +5.0V, unless otherwise stated)

Symbol	Parameter	Test Conditions (Note 4)			Min	Typ.	Max	Unit
V_{UVLO}	Input UVLO	R_{load}=1kΩ			1.6	1.9	2.5	V
I_{SHDN}	Input Shutdown Current	Disabled, I_{OUT}= 0				0.5	1	μA
I_Q	Input Quiescent Current	Enabled, I_{OUT}= 0				45	70	μA
I_{LEAK}	Input Leakage Current	Disabled, OUT grounded					1	μA
I_{REV}	Reverse Leakage Current	Disabled, V_{IN}= 0V, V_{OUT}= 5V, I_{REV} at V_{IN}				0.05		μA
$R_{DS(ON)}$	Switch on-resistance	V_{IN} = 5V, I_{OUT}= 1.5A	T_A = 25°C	MSOP8-EP		90	115	mΩ
				SOP-8L		95	115	
			-40°C ≤ T_A ≤ 85°C				140	
		V_{IN} = 3.3V, I_{OUT}= 1.5A	T_A = 25°C			115	140	
			-40°C ≤ T_A ≤ 85°C				170	
I_{LIMIT}	Over-Load Current Limit	V_{IN}= 5V, V_{OUT}= 4.5V, C_L=120μF			2.1	2.45	2.8	A
I_{Trig}	Current limiting trigger threshold	Output Current Slew rate (<100A/s) , C_L=100μF				2.5		A
I_{SHORT}	Short-Circuit Current Limit	Enabled into short circuit, C_L=100μF				2.5		A
T_{SHORT}	Short-circuit Response Time	V_{OUT} = 0V to I_{OUT} = I_{LIMIT} (short applied to output)				5		μs
V_{IL}	EN Input Logic Low Voltage	V_{IN} = 2.7V to 5.5V					0.8	V
V_{IH}	EN Input Logic High Voltage	V_{IN} = 2.7V to 5.5V			2			V
I_{SINK}	EN Input leakage	V_{EN} = 5V					1	μA
$T_{D(ON)}$	Output turn-on delay time	C_L=1μF, R_{load}=10Ω				50		μs
T_R	Output turn-on rise time	C_L=1μF, R_{load}=10Ω				0.6	1.5	ms
$T_{D(OFF)}$	Output turn-off delay time	C_L=1μF, R_{load}=10Ω				4		μs
T_F	Output turn-off fall time	C_L=1μF, R_{load}=10Ω				0.03	0.1	ms
R_{FLG}	FLG output FET on-resistance	I_{FLG} =10mA, C_L=100μF				20	40	Ω
T_{Blank}	FLG blanking time	C_{IN}=10μF, C_L=100μF			4	7	15	ms
R_{DIS}	Discharge resistance (Note 5)	V_{IN} = 5V, disabled, I_{OUT}= 1mA				290		Ω
T_{SHDN}	Thermal Shutdown Threshold	Enabled, R_{load}=1kΩ				140		°C
T_{HYS}	Thermal Shutdown Hysteresis					25		°C
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOP-8L (Note 6)				110		°C/W
		MSOP-8L-EP (Note 7)				60		°C/W

Notes: 4. Pulse-testing techniques maintain junction temperature close to ambient temperature; thermal effects must be taken into account separately.
5. The discharge function is active when the device is disabled (when enable is de-asserted). The discharge function offers a resistive discharge path for the external storage capacitor. This is suitable only to discharge filter capacitors for limited time and cannot dissipate steady state currents greater than 8mA.
6. Test condition for SOP-8L: Device mounted on FR-4, 2oz copper, with minimum recommended pad layout.
7. Test condition for MSOP-8L-EP: Device mounted on 2" x 2" FR-4 substrate PC board, 2oz copper, with minimum recommended pad on top layer and thermal vias to bottom layer ground plane.

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Typical Performance Characteristics

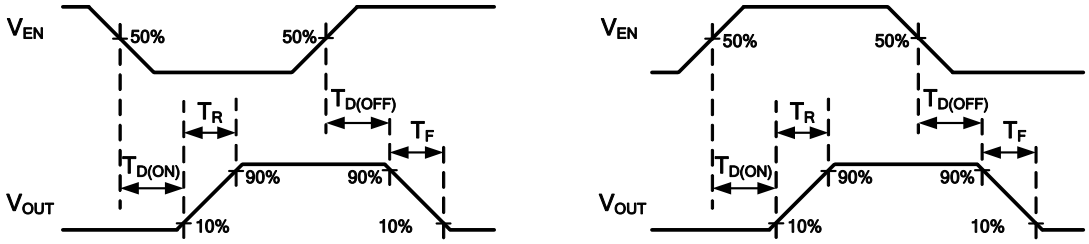


Figure 1. Voltage Waveforms: AP2101 (left), AP2111 (right)

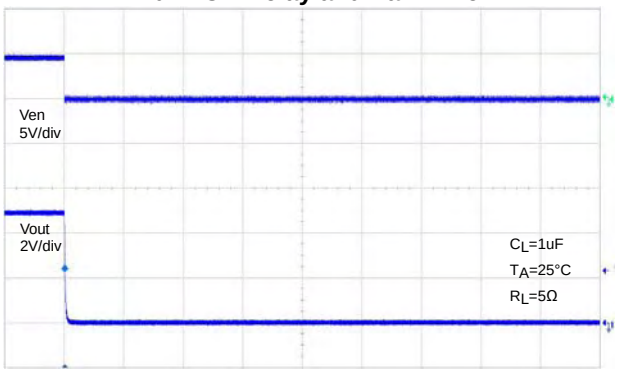
All Enable Plots are for AP2111 Active High

Turn-On Delay and Rise Time



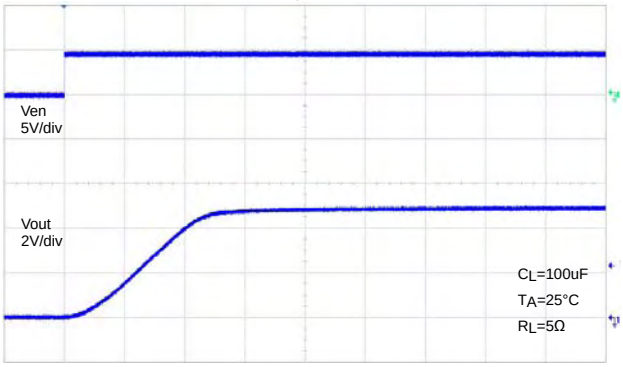
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Turn-Off Delay and Fall Time



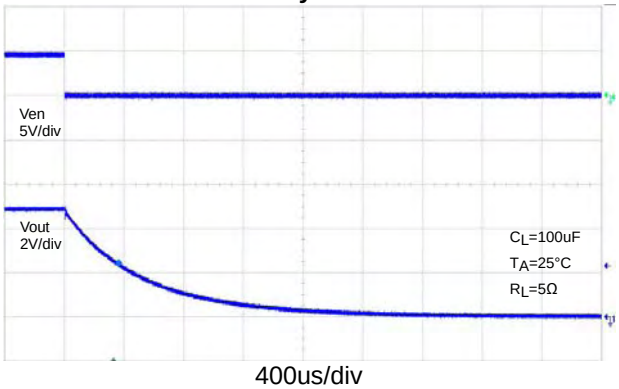
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Turn-On Delay and Rise Time



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Turn-Off Delay and Fall Time

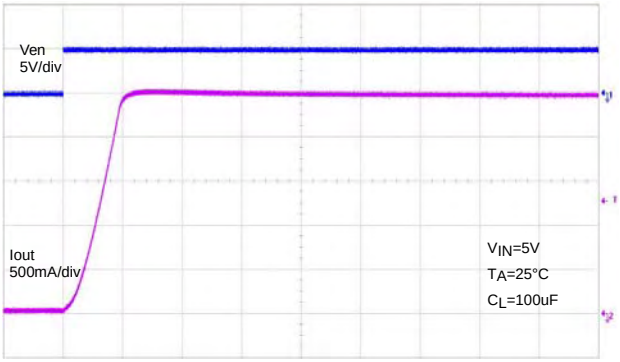


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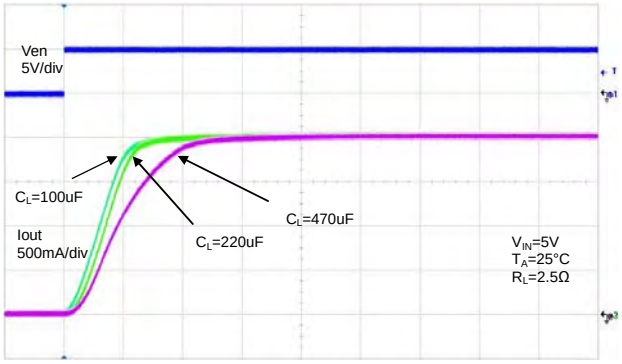
Typical Performance Characteristics (Continued)

Short Circuit Current, Device Enabled Into Short



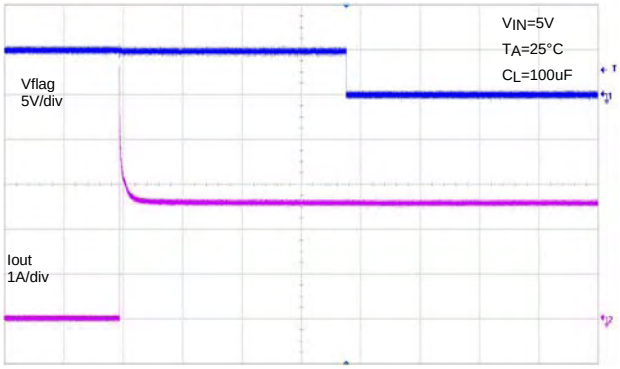
500us/div

Inrush Current



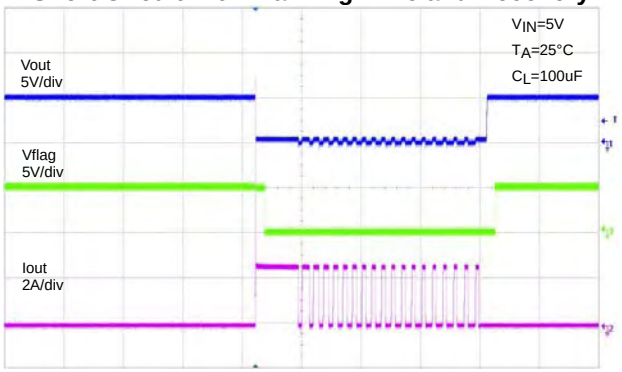
1ms/div

0.6 Ω Load Connected to Enabled Device



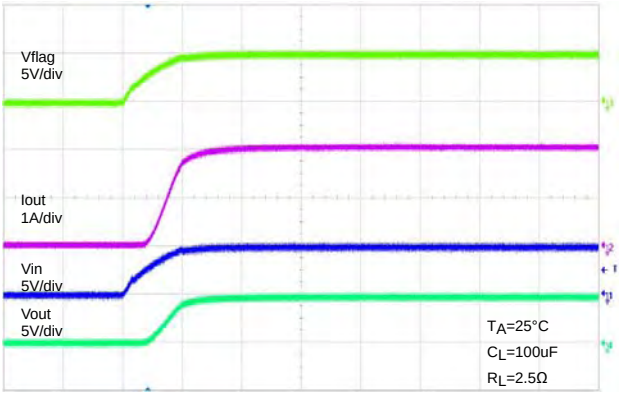
2ms/div

Short Circuit with Blanking Time and Recovery



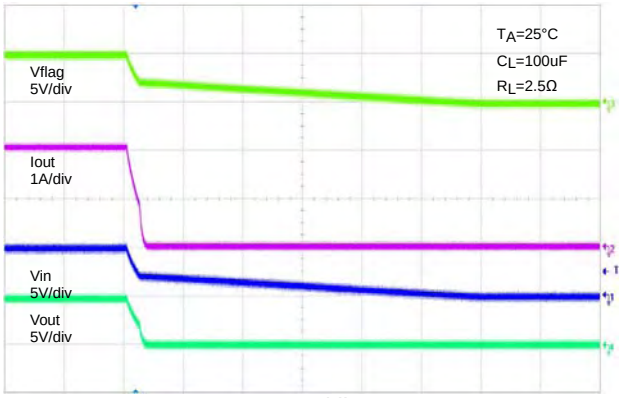
50ms/div

Power On



1ms/div

Power Off

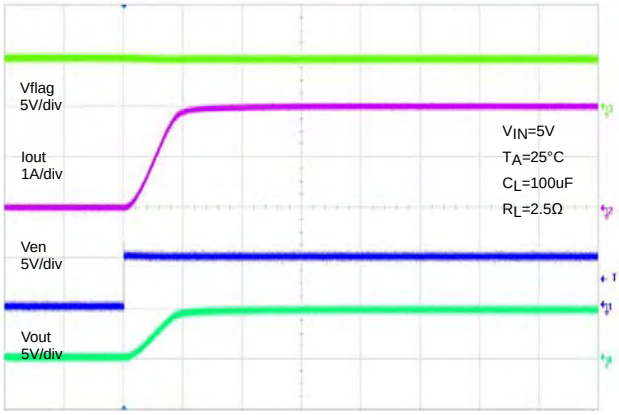


10ms/div

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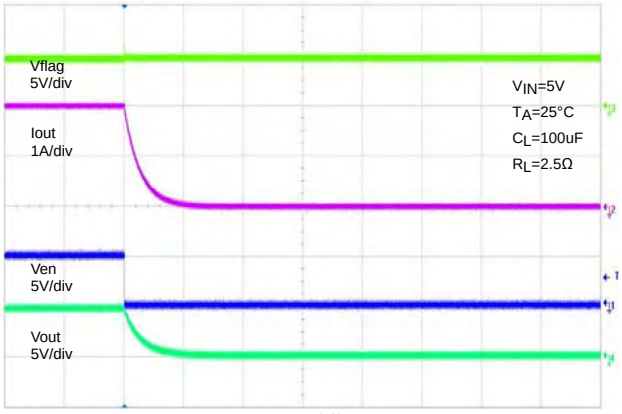
Typical Performance Characteristics (Continued)

Device Enabled



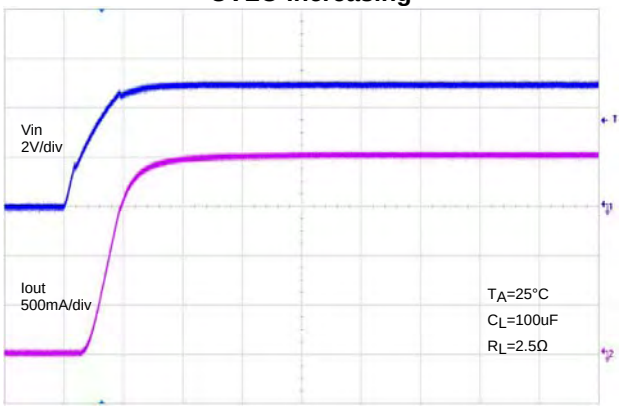
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Device Disabled



1ms/div

UVLO Increasing

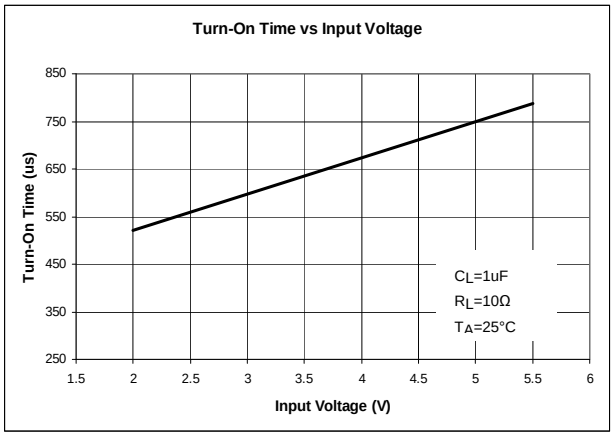


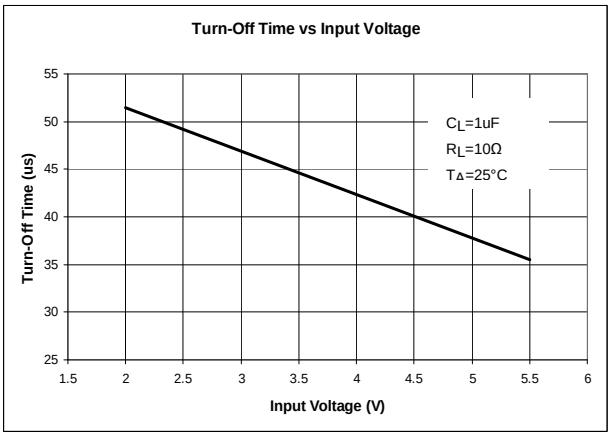
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UVLO Decreasing



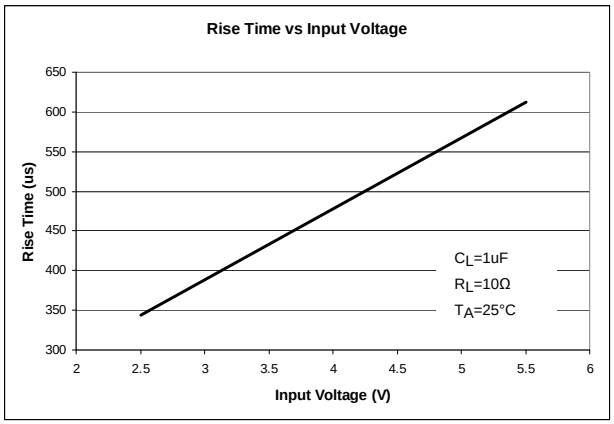
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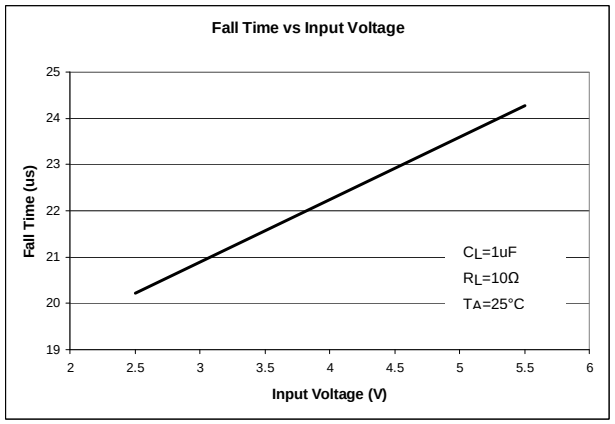


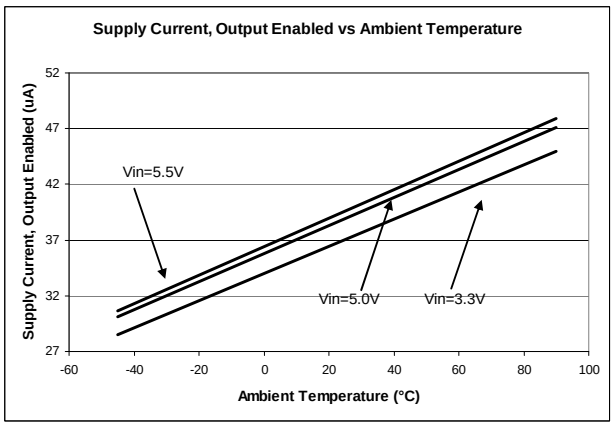


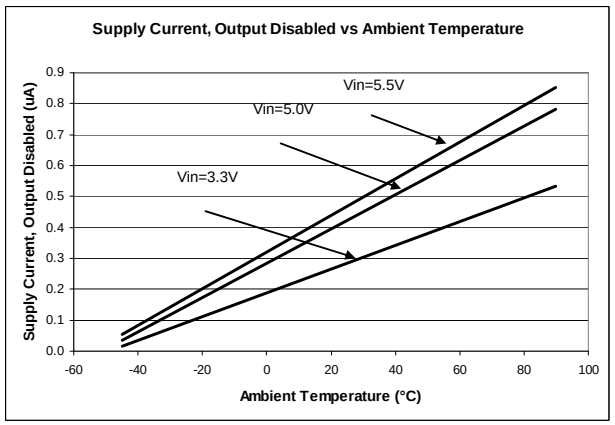
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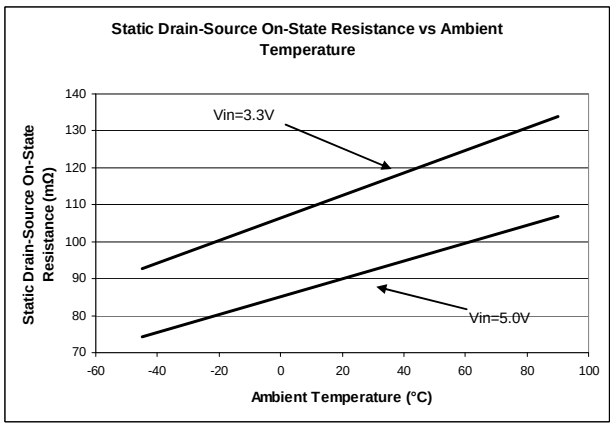
Typical Performance Characteristics (Continued)

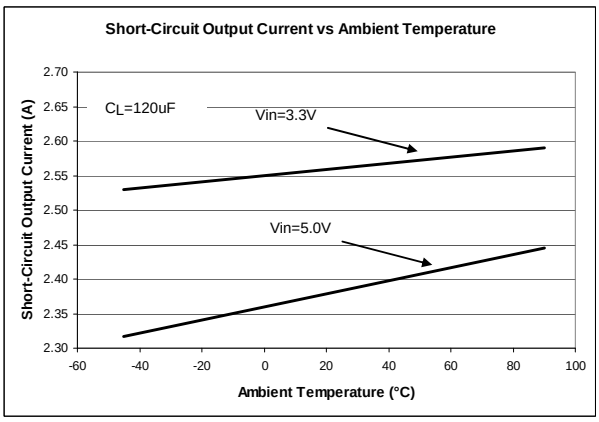






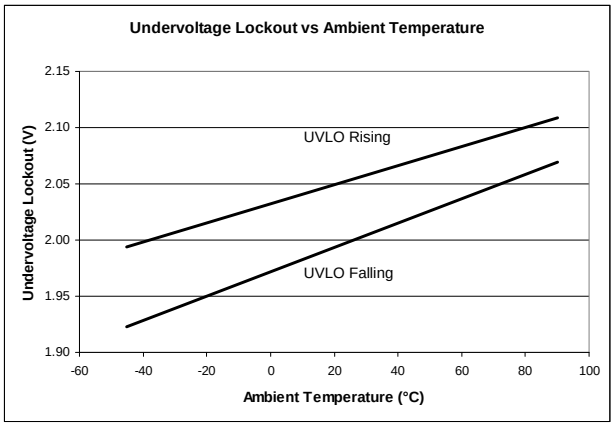


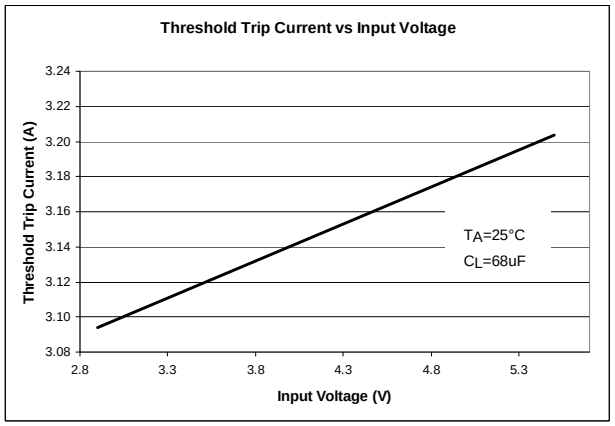


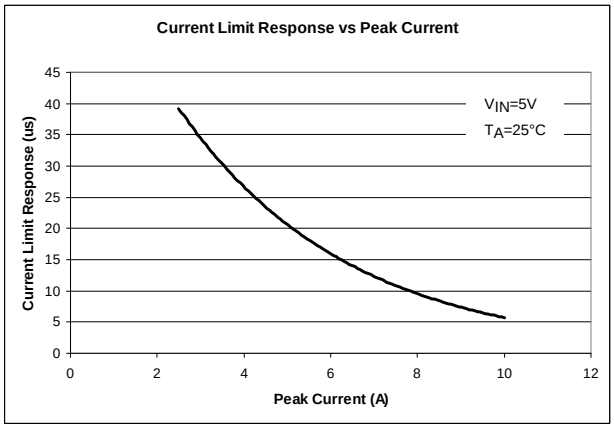


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Typical Performance Characteristics (Continued)







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Application Note

Power Supply Considerations

A 0.1-µF to 1-µF X7R or X5R ceramic bypass capacitor between IN and GND, close to the device, is recommended. Placing a high-value electrolytic capacitor on the input (10-µF minimum) and output pin(s) is recommended when the output load is heavy. This precaution reduces power-supply transients that may cause ringing on the input. Additionally, bypassing the output with a 0.01-µF to 0.1-µF ceramic capacitor improves the immunity of the device to short-circuit transients.

Over-current and Short Circuit Protection

An internal sensing FET is employed to check for over-current conditions. Unlike current-sense resistors, sense FETs do not increase the series resistance of the current path. When an overcurrent condition is detected, the device maintains a constant output current and reduces the output voltage accordingly. Complete shutdown occurs only if the fault stays long enough to activate thermal limiting.

Three possible overload conditions can occur. In the first condition, the output has been shorted to GND before the device is enabled or before V_{IN} has been applied. The AP2101/AP2111 senses the short circuit and immediately clamps output current to a certain safe level namely I_{LIMIT}.

In the second condition, an output short or an overload occurs while the device is enabled. At the instance the overload occurs, higher current may flow for a very short period of time before the current limit function can react. After the current limit function has tripped (reached the over-current trip threshold), the device switches into current limiting mode and the current is clamped at I_{LIMIT}.

In the third condition, the load has been gradually increased beyond the recommended operating current. The current is permitted to rise until the current-limit threshold (I_{TRIG}) is reached or until the thermal limit of the device is exceeded. The AP2101/AP2111 is capable of delivering current up to the current-limit threshold without damaging the device. Once the threshold has been reached, the device switches into its current limiting mode and is set at I_{LIMIT}.

To protect against short circuit to GND at extremely low temperature (< -30°C), a minimum 120-µF electrolytic capacitor on the output pin is recommended. A correct capacitor type with capacitor voltage rating and temperature characteristics must be properly chosen so that capacitance value does not drop too low at the extremely low temperature operation. A recommended capacitor should have temperature characteristics of less than 10% variation of capacitance change when operated at extremely low temp. Our recommended aluminum electrolytic capacitor type is Panasonic FC series.

At low input voltage condition (V_{IN} < 3V), the short circuit protection current may rise as high as twice the typical value.

FLG Response

When an over-current or over-temperature shutdown condition is encountered, the FLG open-drain output goes active low after a nominal 7-ms deglitch timeout. The FLG output remains low until both over-current and over-temperature conditions are removed. Connecting a heavy capacitive load to the output of the device can cause a momentary over-current condition, which does not trigger the FLG due to the 7-ms deglitch timeout. The AP2101/AP2111 is designed to eliminate false over-current reporting without the need of external components to remove unwanted pulses.

Power Dissipation and Junction Temperature

The low on-resistance of the internal MOSFET allows the small surface-mount packages to pass large current. Using the maximum operating ambient temperature (T_A) and $R_{DS(ON)}$, the power dissipation can be calculated by:

$$P_D = R_{DS(ON)} \times I^2$$

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Application Note (Continued)

Finally, calculate the junction temperature:

$T_J = P_D \times R_{\theta JA} + T_A$

Where:

T_A= Ambient temperature °C
$R_{\theta JA}$ = Thermal resistance
P_D = Total power dissipation

Thermal Protection

Thermal protection prevents the IC from damage when heavy-overload or short-circuit faults are present for extended periods of time. The AP2101/AP2111 implements a thermal sensing to monitor the operating junction temperature of the power distribution switch. Once the die temperature rises to approximately 140°C due to excessive power dissipation in an over-current or short-circuit condition the internal thermal sense circuitry turns the power switch off, thus preventing the power switch from damage. Hysteresis is built into the thermal sense circuit allowing the device to cool down approximately 25°C before the switch turns back on. The switch continues to cycle in this manner until the load fault or input power is removed. The FLG open-drain output is asserted when an over-temperature shutdown or over-current occurs with 7-ms deglitch.

Under-voltage Lockout (UVLO)

Under-voltage lockout function (UVLO) keeps the internal power switch from being turned on until the power supply has reached at least 1.9V, even if the switch is enabled. Whenever the input voltage falls below approximately 1.9V, the power switch is quickly turned off. This facilitates the design of hot-insertion systems where it is not possible to turn off the power switch before input power is removed.

Host/Self-Powered HUBs

Hosts and self-powered hubs (SPH) have a local power supply that powers the embedded functions and the downstream ports. This power supply must provide from 5.25V to 4.75V to the board side of the downstream connection under both full-load and no-load conditions. Hosts and SPHs are required to have current-limit protection and must report over-current conditions to the USB controller. Typical SPHs are desktop PCs, monitors, printers, and stand-alone hubs.

Generic Hot-Plug Applications

In many applications it may be necessary to remove modules or pc boards while the main unit is still operating. These are considered hot-plug applications. Such implementations require the control of current surges seen by the main power supply and the card being inserted. The most effective way to control these surges is to limit and slowly ramp the current and voltage being applied to the card, similar to the way in which a power supply normally turns on. Due to the controlled rise times and fall times of the

AP2101/AP2111, these devices can be used to provide a softer start-up to devices being hot-plugged into a powered system. The UVLO feature of the AP2101/AP2111 also ensures that the switch is off after the card has been removed, and that the switch is off during the next insertion.

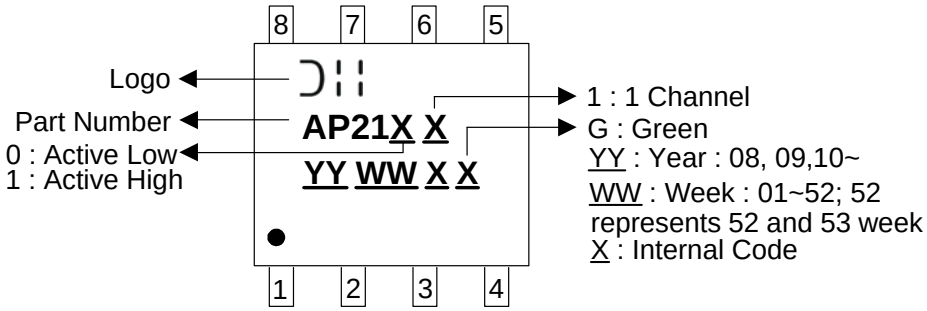
By placing the AP2101/AP2111 between the V_{CC} input and the rest of the circuitry, the input power reaches these devices first after insertion. The typical rise time of the switch is approximately 1ms, providing a slow voltage ramp at the output of the device. This implementation controls system surge current and provides a hot-plugging mechanism for any device.

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Marking Information

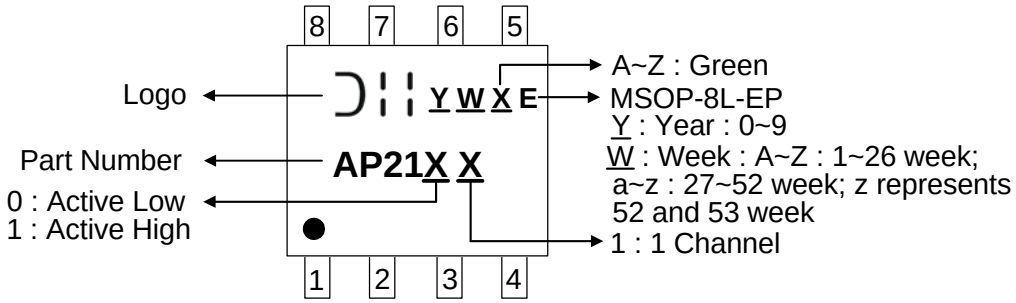
(1) SOP-8L

(Top view)



(2) MSOP-8L-EP

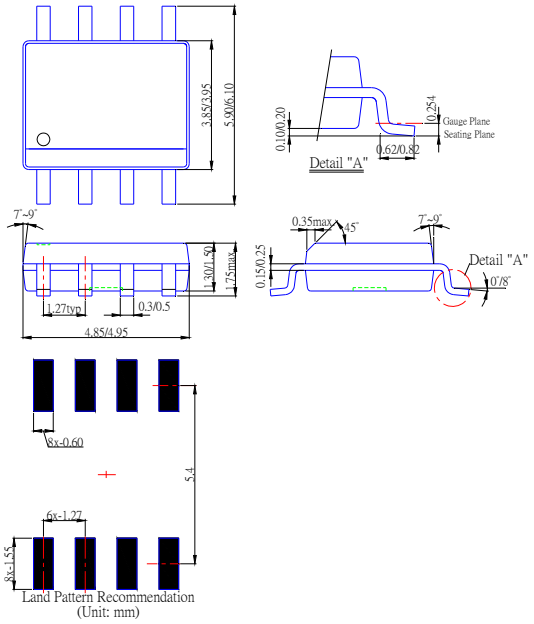
(Top view)



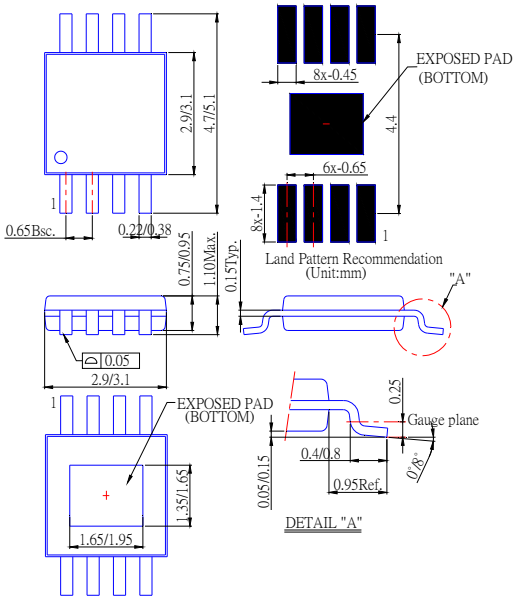
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Package Information (All Dimensions in mm)

(1) Package Type: SOP-8L



(2) Package Type: MSOP-8L-EP



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